

NL27WZ06

Dual Inverter with Open Drain Outputs

The NL27WZ06 is a high performance dual inverter with open drain outputs operating from a 2.3 to 5.5 V supply.

The internal circuit is composed of multiple stages, including an open drain output which provides the capability to set output switching level. This allows the NL27WZ06 to be used to interface 5 V circuits to circuits of any voltage between V_{CC} and 7 V using an external resistor and power supply.

- Extremely High Speed: t_{PD} 2.5 ns (typical) at $V_{CC} = 5$ V
- Designed for 2.3 V to 5.5 V V_{CC} Operation
- Over Voltage Tolerant Inputs
- LVTTL Compatible – Interface Capability With 5 V TTL Logic with $V_{CC} = 3$ V
- LVC MOS Compatible
- 24 mA Output Sink Capability
- Near Zero Static Supply Current Substantially Reduces System Power Requirements
- Chip Complexity: FET = 72; Equivalent Gate = 18

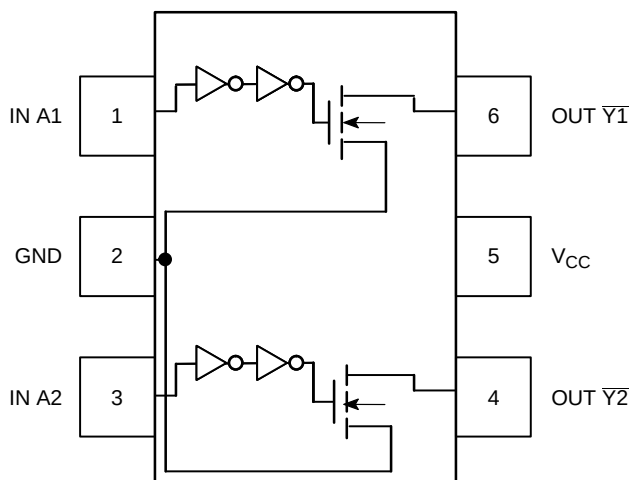


Figure 1. Pinout (Top View)

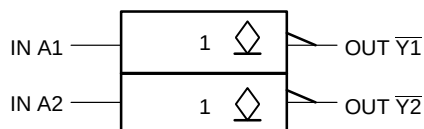


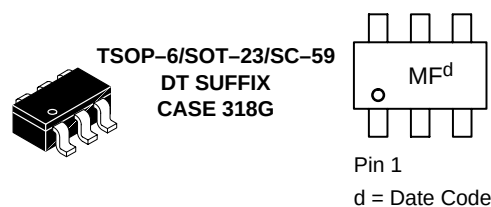
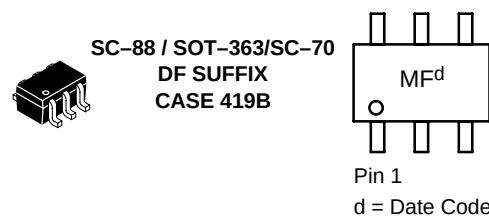
Figure 2. Logic Symbol



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MARKING DIAGRAMS



PIN ASSIGNMENT

1	IN A1
2	GND
3	IN A2
4	OUT $\bar{Y}2$
5	V_{CC}
6	OUT $\bar{Y}1$

FUNCTION TABLE

A Input	$\bar{Y}$ Output
L	Z
H	L

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

NL27WZ06

MAXIMUM RATINGS (Note 1.)

Symbol	Characteristics	Value	Unit
V _{CC}	DC Supply Voltage	−0.5 to +7.0	V
V _I	DC Input Voltage	−0.5 ≤ V _I ≤ +7.0	V
V _O	DC Output Voltage Output in Z or LOW State (Note 2.)	−0.5 ≤ V _O ≤ 7.0	V
I _{IK}	DC Input Diode Current V _I < GND	−50	mA
I _{OK}	DC Output Diode Current V _O < GND	−50	mA
I _O	DC Output Sink Current	±50	mA
I _{CC}	DC Supply Current Per Supply Pin	±100	mA
I _{GND}	DC Ground Current Per Ground Pin	±100	mA
T _{STG}	Storage Temperature Range	−65 to +150	°C
P _D	Power Dissipation in Still Air SC−88, TSOP−6	200	mW
θ _{JA}	Thermal resistance SC−88, TSOP−6	333	°C/W
T _L	Lead temperature, 1 mm from case for 10 s	260	°C
T _J	Junction temperature under bias	+150	°C
V _{ESD}	ESD Withstand Voltage Human Body Model (Note 3.) Machine Model (Note 4.) Charged Device Model (Note 5.)	> 2000 > 200 N/A	V
I _{Latch-Up}	Latch-Up Performance Above V _{CC} and Below GND at 85°C (Note 6.)	±500	mA

1. Absolute maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute–maximum–rated conditions is not implied.
2. I_O absolute maximum rating must be observed.
3. Tested to EIA/JESD22–A114–A
4. Tested to EIA/JESD22–A115–A
5. Tested to JESD22–C101–A
6. Tested to EIA/JESD78

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	Supply Voltage Operating Data Retention Only	2.3 1.5	5.5 5.5	V
V _I	Input Voltage	0	5.5	V
V _O	Output Voltage (Z or LOW State)	0	5.5	V
T _A	Operating Free–Air Temperature	−40	+85	°C
Δt/ΔV	Input Transition Rise or Fall Rate V _{CC} = 2.5 V ±0.2 V V _{CC} = 3.0 V ±0.3 V V _{CC} = 5.0 V ±0.5 V	0 0 0	20 10 5	ns/V

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Condition	V _{CC} (V)	T _A = 25°C			-40°C ≤ T _A ≤ 85°C		Unit
				Min	Typ	Max	Min	Max	
V _{IH}	High-Level Input Voltage		2.3 to 5.5	0.7 V _{CC}			0.7 V _{CC}		V
V _{IL}	Low-Level Input Voltage		2.3 to 5.5			0.3 V _{CC}		0.3 V _{CC}	V
I _{LKG}	Z-State Output Leakage Current	V _{IN} = V _{IL} V _{OUT} = V _{CC} or GND	2.3 to 5.5			±5.0		±10.0	μA
V _{OL}	Low-Level Output Voltage V _{IN} = V _{IH} or V _{IL}	I _{OL} = 100 μA	2.3 to 5.5			0.1		0.1	V
		I _{OL} = 8 mA	2.3		0.22	0.3		0.3	
		I _{OL} = 12 mA	2.7		0.22	0.4		0.4	
		I _{OL} = 16 mA	3.0		0.28	0.4		0.4	
		I _{OL} = 24 mA	3.0		0.38	0.55		0.55	
		I _{OL} = 32 mA	4.5		0.42	0.55		0.55	
I _{IN}	Input Leakage Current	V _{IN} or V _{OUT} = V _{CC} or GND	0 to 5.5			±0.1		±1.0	μA
I _{OFF}	Power Off-Output Leakage Current	V _{OUT} = 5.5 V	0			1		10	μA
I _{CC}	Quiescent Supply Current	V _{IN} = V _{CC} or GND	5.5			1		10	μA

AC ELECTRICAL CHARACTERISTICS t_R = t_F = 2.5 ns; C_L = 50 pF; R_L = 500 Ω

Symbol	Parameter	Condition	V _{CC} (V)	T _A = 25°C			-40°C ≤ T _A ≤ 85°C		Unit
				Min	Typ	Max	Min	Max	
t _{PZL}	Propagation Delay (Figure 3 and 4)	R _L = R ₁ = 500 Ω, C _L = 50 pF	2.5 ± 0.2	0.8	3.0	3.6	0.8	4.1	ns
		R _L = R ₁ = 500 Ω, C _L = 50 pF	3.3 ± 0.3	0.8	2.4	3.2	0.8	3.7	
		R _L = R ₁ = 500 Ω, C _L = 50 pF	5.0 ± 0.5	0.5	2.4	3.0	0.5	3.5	
t _{PLZ}	Propagation Delay (Figure 3 and 4)	R _L = R ₁ = 500 Ω, C _L = 50 pF	2.5 ± 0.2	0.8	2.5	3.6	0.8	4.1	ns
		R _L = R ₁ = 500 Ω, C _L = 50 pF	3.3 ± 0.3	0.8	2.1	3.2	0.8	3.7	
		R _L = R ₁ = 500 Ω, C _L = 50 pF	5.0 ± 0.5	0.5	1.2	3.0	0.5	3.5	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C _{IN}	Input Capacitance	V _{CC} = 5.5 V, V _I = 0 V or V _{CC}	2.5	pF
C _{OUT}	Output Capacitance	V _{CC} = 5.5 V, V _I = 0 V or V _{CC}	4	pF
C _{PD}	Power Dissipation Capacitance (Note 7.)	10 MHz, V _{CC} = 5.5 V, V _I = 0 V or V _{CC}	4	pF

7. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no-load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

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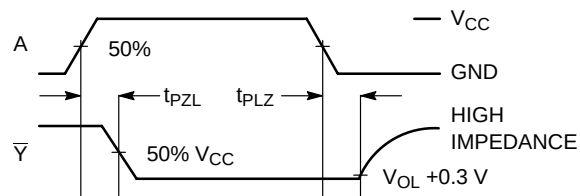


Figure 3. Switching Waveforms

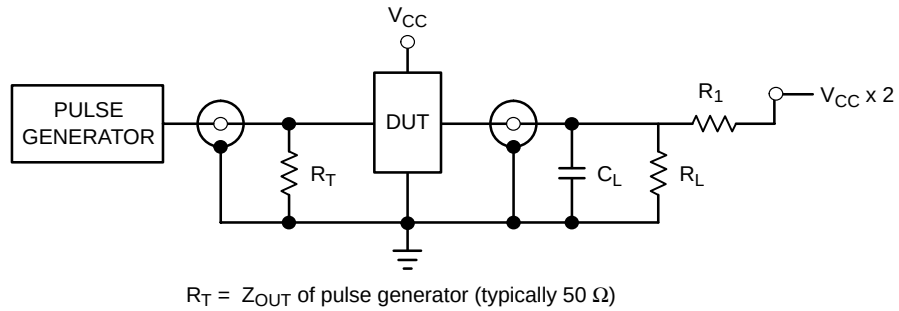


Figure 4. Test Circuit

DEVICE ORDERING INFORMATION

Device Order Number	Device Nomenclature							Package Type (Name/SOT#/Common Name)	Tape and Reel Size
	Logic Circuit Indicator	No. of Gates per Package	Temp Range Identifier	Technology	Device Function	Package Suffix	Tape & Reel Suffix		
NL27WZ06DFT2	NL	2	7	WZ	06	DF	T2	SC-88 / SOT-363 / SC-70	178 mm (7") 3000 Unit
NL27WZ06DTT1	NL	2	7	WZ	06	DT	T1	TSOP-6 / SOT-23 / SC-59	178 mm (7") 3000 Unit

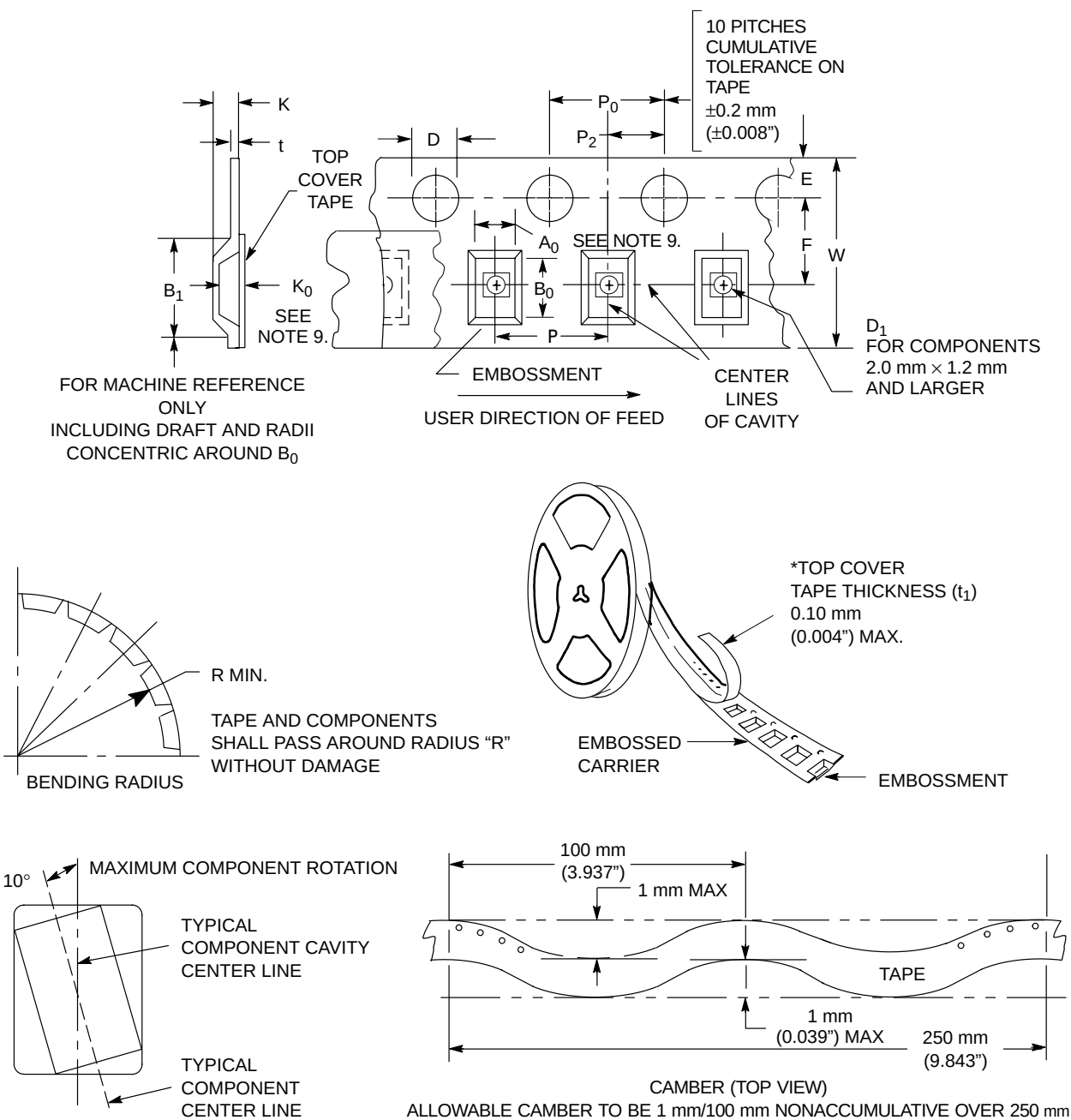


Figure 5. Carrier Tape Specifications

EMBOSSED CARRIER DIMENSIONS (See Notes 8. and 9.)

Tape Size	B ₁ Max	D	D ₁	E	F	K	P	P ₀	P ₂	R	T	W
8 mm	4.35 mm (0.171")	1.5 +0.1/-0.0 mm (0.059 +0.004/-0.0")	1.0 mm Min (0.039")	1.75 ±0.1 mm (0.069 ±0.004")	3.5 ±0.5 mm (1.38 ±0.002")	2.4 mm (0.094")	4.0 ±0.10 mm (0.157 ±0.004")	4.0 ±0.1 mm (0.156 ±0.004")	2.0 ±0.1 mm (0.079 ±0.002")	25 mm (0.98")	0.3 ±0.05 mm (0.01 +0.0038/-0.0002")	8.0 ±0.3 mm (0.315 ±0.012")

8. Metric Dimensions Govern—English are in parentheses for reference only.

9. A₀, B₀, and K₀ are determined by component size. The clearance between the components and the cavity must be within 0.05 mm min to 0.50 mm max. The component cannot rotate more than 10° within the determined cavity

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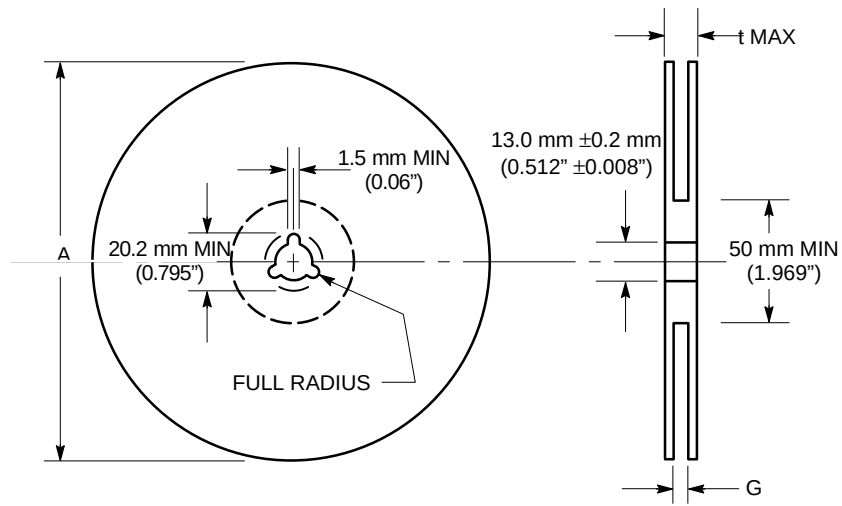


Figure 6. Reel Dimensions

REEL DIMENSIONS

Tape Size	T&R Suffix	A Max	G	t Max
8 mm	T1, T2	178 mm (7")	8.4 mm, +1.5 mm, -0.0 (0.33" + 0.059", -0.00)	14.4 mm (0.56")

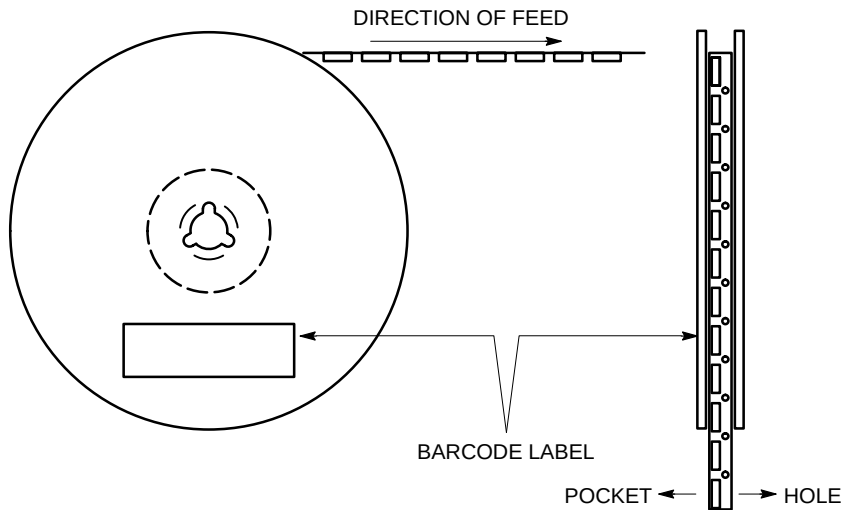


Figure 7. Reel Winding Direction

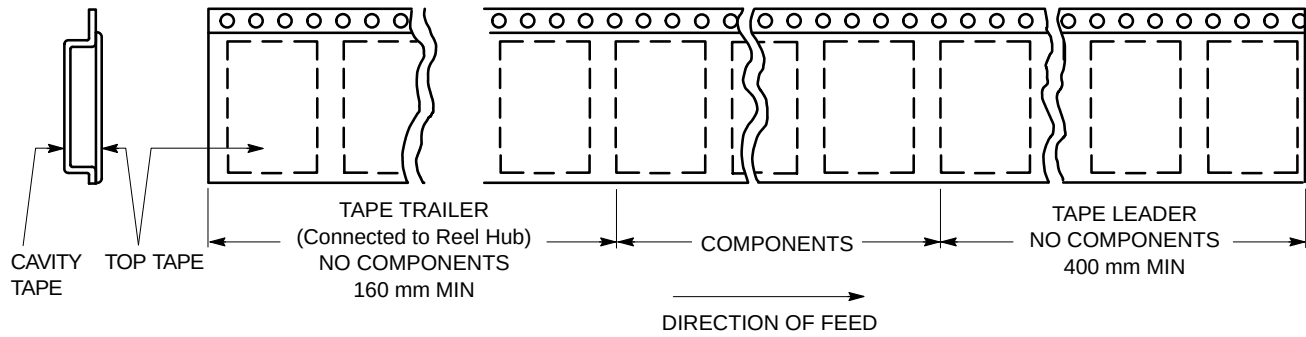


Figure 8. Tape Ends for Finished Goods

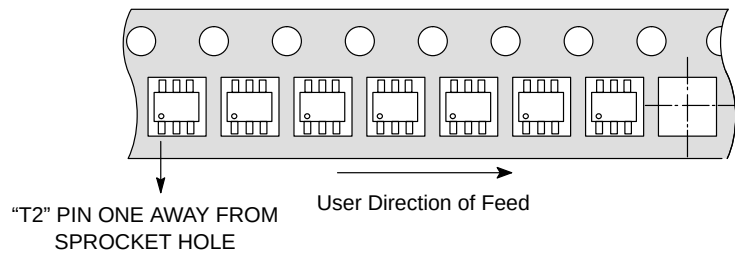


Figure 9. DFT2 (SC-88) Reel Configuration/Orientation

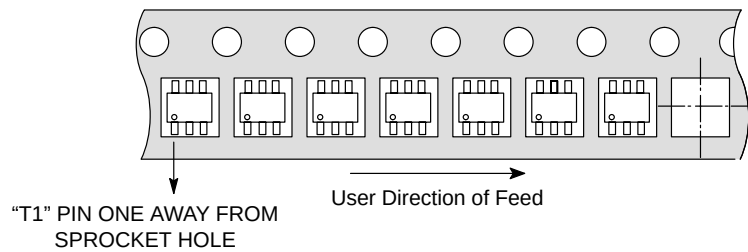


Figure 10. DTT1 (TSOP-6) Reel Configuration/Orientation

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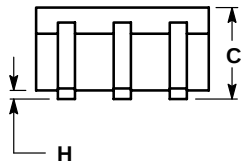
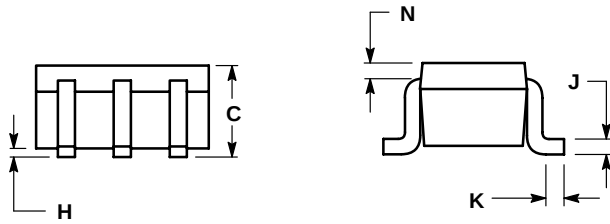
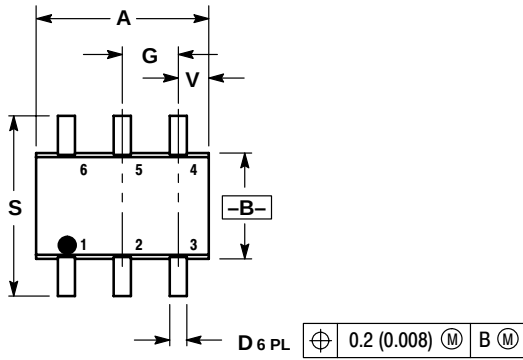
PACKAGE DIMENSIONS

SC-88/SOT-363/SC-70

DF SUFFIX

CASE 419B-01

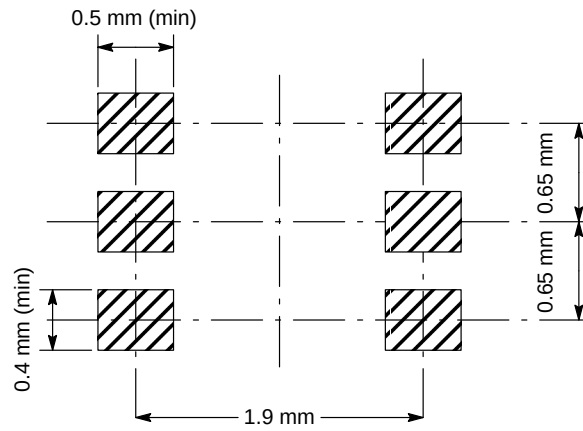
ISSUE G



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.071	0.087	1.80	2.20
B	0.045	0.053	1.15	1.35
C	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026 BSC		0.65 BSC	
H	---	0.004	---	0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008 REF		0.20 REF	
S	0.079	0.087	2.00	2.20
V	0.012	0.016	0.30	0.40



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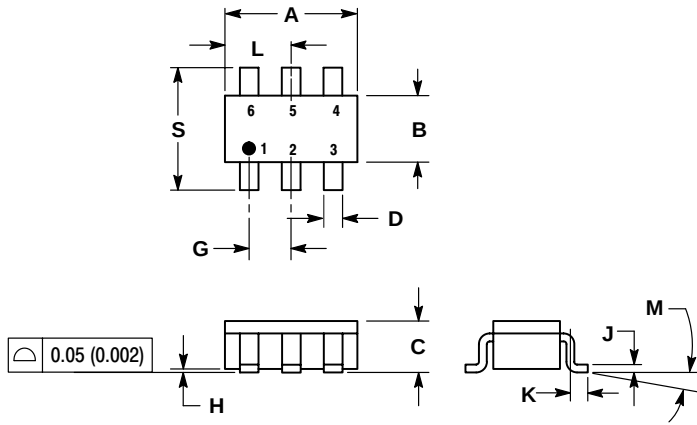
PACKAGE DIMENSIONS

TSOP-6/SOT-23/SC-59

DT SUFFIX

CASE 318G-02

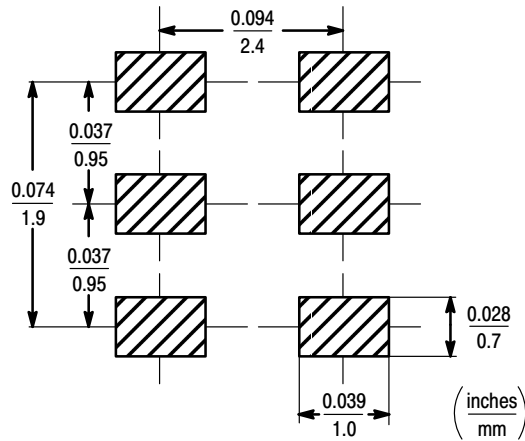
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NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.90	3.10	0.1142	0.1220
B	1.30	1.70	0.0512	0.0669
C	0.90	1.10	0.0354	0.0433
D	0.25	0.50	0.0098	0.0197
G	0.85	1.05	0.0335	0.0413
H	0.013	0.100	0.0005	0.0040
J	0.10	0.26	0.0040	0.0102
K	0.20	0.60	0.0079	0.0236
L	1.25	1.55	0.0493	0.0610
M	0°	10°	0°	10°
S	2.50	3.00	0.0985	0.1181



Notes

Notes

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